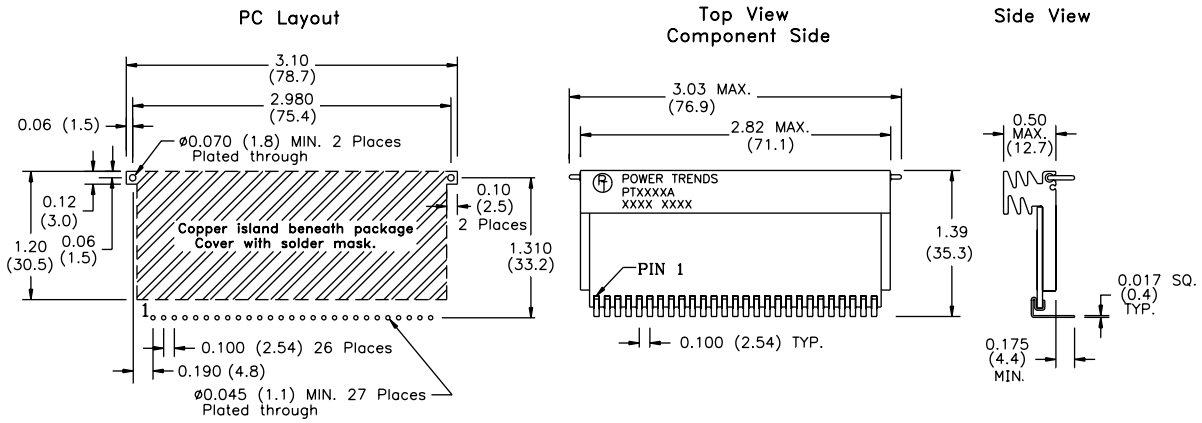
Package Style 810

Suffix A, C

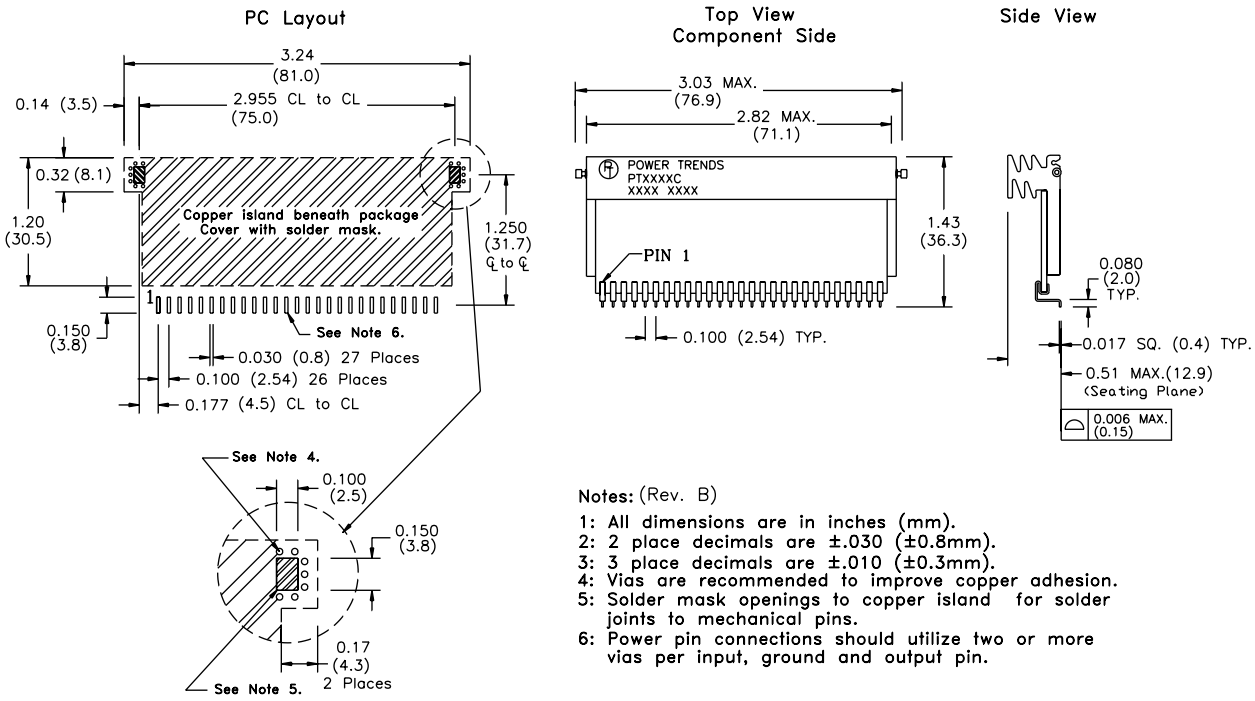
(Revised 6/30/2000)

PACKAGE INFORMATION AND DIMENSIONS

Horizontal Through–Hole Mount (Suffix A)



Surface Mount (Suffix C)



Notes: (Rev. B)

1: All dimensions are in inches (mm).
2: 2 place decimals are ±.030 (±0.8mm).
3: 3 place decimals are ±.010 (±0.3mm).
4: Vias are recommended to improve copper adhesion.
5: Solder mask openings to copper island for solder joints to mechanical pins.
6: Power pin connections should utilize two or more vias per input, ground and output pin.